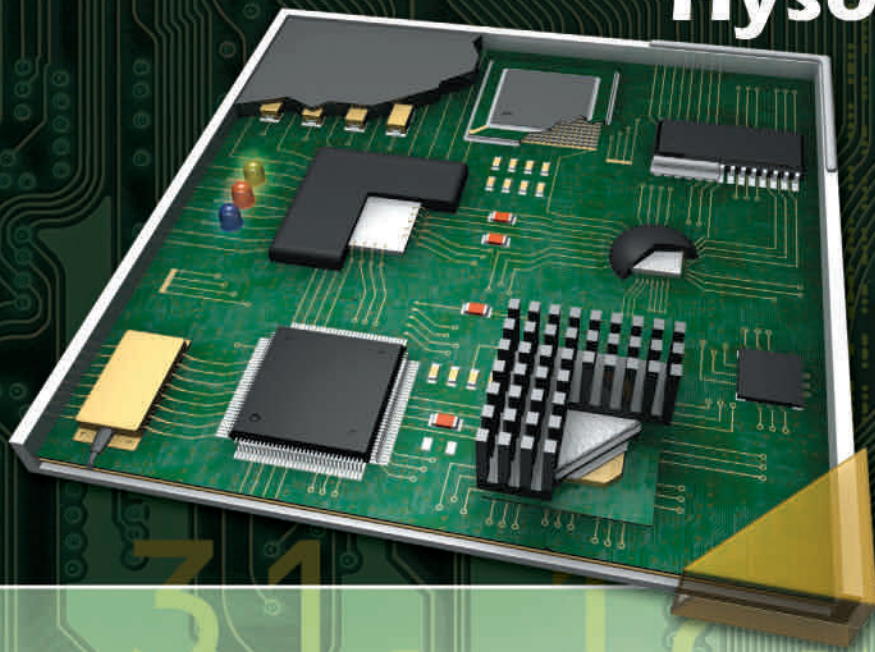


# Hysol®

# LOCTITE

# Multicore



## Get It Right the First Time

*A New Approach to Package Design and Production Reliability*

### Innovative Modeling and Prototyping Services from Henkel Corporation

Understand optimal materials sets for various substrates; develop better and more reliable packages; obtain critical test data – all before investing in large-scale package production!

Sound too good to be true? Not anymore. Henkel offers a new service that allows customers to fully understand and evaluate IC packages while still in the design phase – before going to all of the production expense of package manufacture. How many times have you put a package into production only to find out that your selected materials didn't work with the substrate? These are expensive lessons that Henkel can help you avoid.

#### Visionary Technology for Next-Generation Manufacturing

By partnering with customers early in the product development process, Henkel technical experts can adapt an IC package design to ensure optimum performance between substrates and critical packaging and assembly materials. With our modeling and computer simulation software, Henkel evaluates synergies between specified substrates and various materials. This means that you can now create an IC package by accessing performance data on best-in-class, currently available materials instead of forcing materials to perform within pre-existing design constraints.

#### Reduce Risk and Enjoy “No Surprises” Manufacturing

This amazing technology ensures that you minimize your investment and maximize your return. In Henkel's state-of-the-art laboratory facilities, our engineers work with customers to take new or redesigned products from initial computer models to prototype test packages.

Our exclusive process includes in-house prototype package builds that reduce your test sample production costs and shorten the time required to take a new package from design to test. Once test samples are built, our team of experts performs stress analysis, reliability and failure analysis testing, allowing customers to make critical decisions about which materials will best function in real-world applications.

To find out more about this valuable service from Henkel Corporation, visit [www.electronics.henkel.com](http://www.electronics.henkel.com) or contact our nearest Engineering Center.





## Global Service and Personalized Customer Support

With investment in a global network of advanced analytical labs, Henkel is poised to deliver customers with the most sophisticated technical capabilities, while ensuring worldwide support.

### Current Applications Lab Locations:

Irvine, CA	Singapore
Hemel Hempstead, UK	Yantai, China
Seoul, Korea	Yokohama, Japan
Shanghai, China ( <i>Future Lab Location</i> )	

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## The Most Advanced Analytical Resources

Henkel technical experts have established the finest analytical and applications labs with the most sophisticated equipment available in today's market, again maintaining the highest standards for customers.

### Henkel Corporation Electronics

15350 Barranca Pkwy  
Irvine, CA 92618  
Tel: 949-789-2500  
fax: 949-789-2595

### Henkel Technologies House, Woodlane End

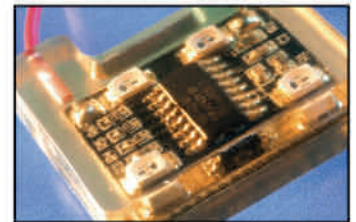
Hemel Hempstead  
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### Henkel (China) Company Ltd

1001-1004, 10/F, Gangtai Plaza  
700 East Yan An Road  
Shanghai, China 200001  
Tel: +86 21 5385 0165  
Fax: +86 21 6360 6070

### Analytical Capabilities

- 2-D and 3-D Finite Element Analysis
- Package Design and Analysis
- DOE Study (materials or design)
- Trend Simulations
- Failure Analysis
- Material Set Recommendation to meet Reliability Specs
- In-House Build Simulation
- Chip Scale Placement
- Die Bonding
- Solder Reflow
- Temperature Cycling
- Temperature Shock
- Shadow Interferometry
- SEM
- CSAM
- FTIR
- HAST
- Laser Profilometer
- Assembly Cleaning
- Dispensing
- Flux and Wave Solder Testing
- Complete Curing Capabilities, Thermal, UV
- Surface and Volume Resistivity Testing
- Stencil and Screen Printing
- High Speed Video Monitoring
- Surface Mount and Chip Scale Rework



[electronics.henkel.com](http://electronics.henkel.com)